

Title (en)

METHOD FOR SIMULTANEOUSLY OBTAINING A PAIR OF SUBSTRATES COVERED BY A USEFUL LAYER

Title (de)

VERFAHREN ZUR GLEICHZEITIGEN HERSTELLUNG EINES MIT EINER NUTZSCHICHT BEDECKTEN SUBSTRATPAARS.

Title (fr)

PROCEDE D'OBTENTION CONCOMITANTE D'UNE PAIRE DE SUBSTRATS RECOUVERTS D'UNE COUCHE UTILE

Publication

EP 1631983 A1 20060308 (FR)

Application

EP 04767237 A 20040603

Priority

- FR 2004001368 W 20040603
- FR 0306845 A 20030606

Abstract (en)

[origin: US2004248378A1] A method for concurrently producing at least a pair of semiconductor structures that each include at least one useful layer on a substrate. The method includes providing an initial structure that includes a useful layer having a front face on a support substrate. Atomic species are implanted into the useful layer to a controlled mean implantation depth to form a zone of weakness within the useful layer that defines first and second useful layers. Next, a stiffening substrate is bonded to the front face of the initial structure. The first useful layer is then detached from the second useful layer along the zone of weakness to obtain a pair of semiconductor structures with a first structure including the stiffening substrate and the first useful layer and a second structure including the support substrate and the second useful layer. The structures obtained can be used in the fields of electronics, optoelectronics or optics.

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Citation (search report)

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